

**1024-BIT LOW POWER BIPOLAR RAM (1024X1)****82LS10/93L415 (O.C.)**  
**82LS11/93L425 (T.S.)**

82LS10/82LS11-F,N, • 93L415/93L425-F,N

**DESCRIPTION**

This family of low power 1024x1 Rams with a typical access time of 30ns, are ideal for cache buffer applications and for systems requiring very high speed main memory.

These products require a single +5V power supply and feature very low current pnp input structures. They include on-chip decoding and a chip enable input for ease of memory expansion, and feature either open collector or tri-state outputs for optimization of word expansion in bused organizations.

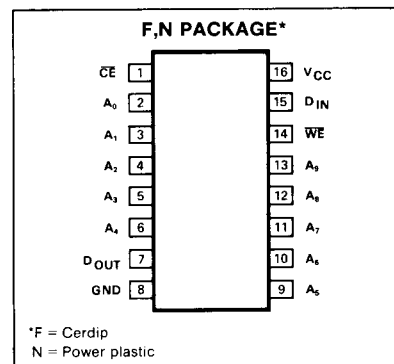
All devices are available in the commercial temperature range (0°C to +75°C), and military temperature range (-55°C to +125°C).

**FEATURES**

- Address access time: 45ns max
- Write cycle time: 45ns max
- Power dissipation: 0.2mW/bit typ
- Input loading: -250µA max
- On-chip address decoding
- Output options:  
82LS10, 93L415: Open collector  
82LS11, 93L425: Tri-state
- Non-inverting output
- Blanked output during Write
- Fully TTL compatible

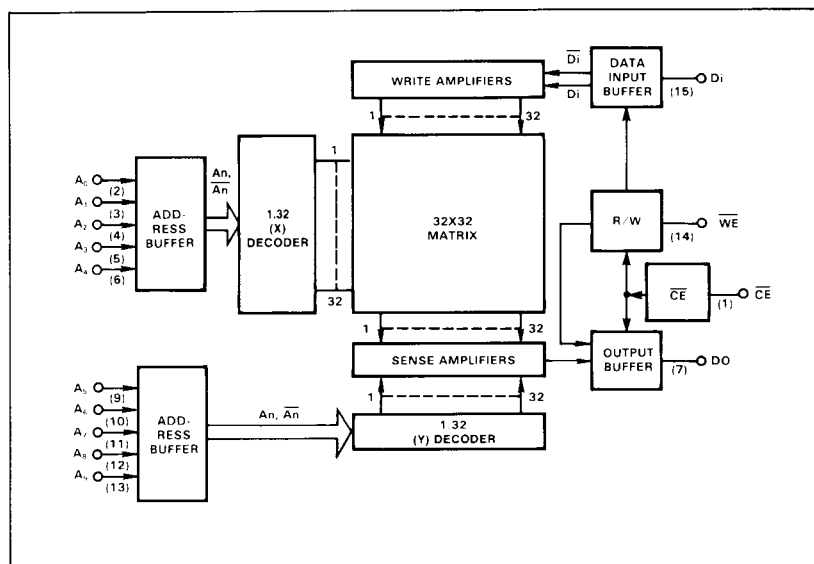
**APPLICATIONS**

- High speed main frame
- Cache memory
- Buffer storage
- Writable control store

**PIN CONFIGURATION****TRUTH TABLE**

MODE	CE	WE	DIN	DOUT	
				82LS10/93L415	82LS11/93L425
Read	0	1	X	Stored data	Stored data
Write low	0	0	0	1	High-Z
Write high	0	0	1	1	High-Z
Disabled	1	X	X	1	High-Z

X = Don't care

**BLOCK DIAGRAM**

**1024-BIT LOW POWER BIPOLAR RAM (1024X1)**

11754 82LS10/93L415 (O.C.)

11762 82LS11/93L425 (T.S.)

82LS10/82LS11-F,N • 93L415/93L425-F,N

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER <sup>1</sup>	RATING	UNIT
V <sub>CC</sub> Supply voltage	+7	Vdc
V <sub>IN</sub> Input voltage	+5.5	Vdc
Output voltage		Vdc
V <sub>OH</sub> High 82LS10/93L415	+5.5	
V <sub>O</sub> Off-state 82LS11/93L425	+5.5	
Temperature range		°C
T <sub>A</sub> Operating		
N Grade	0 to +75	
S Grade	-55 to +125	
T <sub>STG</sub> Storage	-65 to +150	

**DC ELECTRICAL CHARACTERISTICS<sup>9</sup>** N Grade: 0°C ≤ T<sub>A</sub> ≤ +75°C, 4.75V ≤ V<sub>CC</sub> ≤ 5.25V  
S Grade: -55°C ≤ T<sub>A</sub> ≤ +125°C, 4.5V ≤ V<sub>CC</sub> ≤ 5.5V

PARAMETER	TEST CONDITIONS	N82LS10/11 N93L415/425			S82LS10/11 S93L415/425			UNIT
		Min	Typ <sup>2</sup>	Max	Min	Typ <sup>2</sup>	Max	
Input voltage								V
V <sub>IL</sub> Low <sup>1</sup>	V <sub>CC</sub> = Min			.85			.80	
V <sub>IH</sub> High <sup>1</sup>	V <sub>CC</sub> = Max	2.1			2.1			
V <sub>IC</sub> Clamp <sup>1,3</sup>	V <sub>CC</sub> = Min, I <sub>IN</sub> = -12mA		-1.0	-1.5		-1.0	-1.5	
Output voltage								V
V <sub>OL</sub> Low <sup>1,4</sup>	V <sub>CC</sub> = Min I <sub>OL</sub> = 16mA		0.35	0.45		0.35	0.50	
V <sub>OH</sub> High (Tri-state) <sup>1,5</sup>	I <sub>OH</sub> = -2mA	2.4			2.4			
Input current								μA
I <sub>IL</sub> Low	V <sub>IN</sub> = 0.45V		-10	-250		-10	-250	
I <sub>IH</sub> High	V <sub>IN</sub> = 5.5V		1	25		1	40	
Output current								μA
I <sub>OLK</sub> Leakage (Open collector) <sup>6</sup>	V <sub>CC</sub> = Max V <sub>OUT</sub> = 5.5V		1	40		1	60	
I <sub>O(OFF)</sub> Hi-Z state (Tri-state) <sup>6</sup>	V <sub>OUT</sub> = 5.5V		1	60		1	100	
I <sub>OS</sub> Short circuit (Tri-state) <sup>7</sup>	V <sub>OUT</sub> = 0.45V V <sub>OUT</sub> = 0V	-20		-60	-20		-100	
I <sub>CC</sub> V <sub>CC</sub> supply current <sup>8</sup>	V <sub>CC</sub> = Max 0 < T <sub>A</sub> < 25°C T <sub>A</sub> ≥ 25°C T <sub>A</sub> ≤ 0°C							mA
				65			75	
Capacitance								pF
C <sub>IN</sub> Input	V <sub>CC</sub> = 5.0V V <sub>IN</sub> = 2.0V		7			4		
C <sub>OUT</sub> Output	V <sub>OUT</sub> = 2.0V							

**BIPOLAR MEMORY**

**1024-BIT LOW POWER BIPOLAR RAM (1024X1)****82LS10/93L415 (O.C.)****82LS11/93L425 (I.S.)**

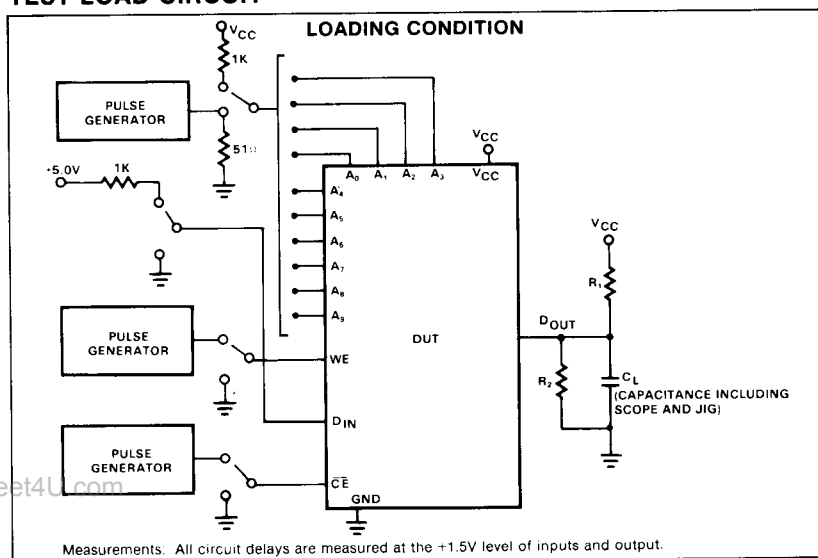
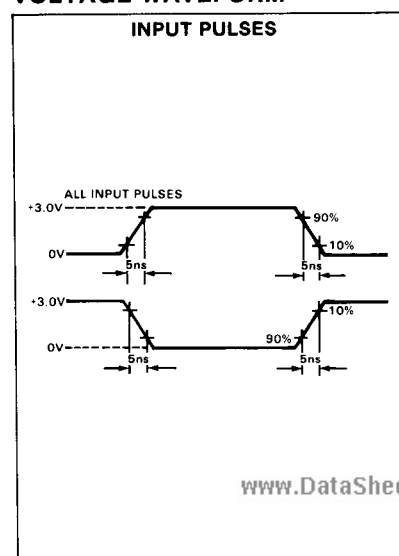
82LS10/82LS11-F,N, • 93L415/93L425-F,N

**AC ELECTRICAL CHARACTERISTICS<sup>9</sup>**  $R_1 = 270\Omega$ ,  $R_2 = 600\Omega$ ,  $C_L = 30pF$ . See ac test load  
N Grade:  $0^\circ C \leq T_A \leq 75^\circ C$ ,  $4.75V \leq V_{CC} \leq 5.25V$   
S Grade:  $-55^\circ C \leq T_A \leq 125^\circ C$ ,  $4.5V \leq V_{CC} \leq 5.5V$ 

PARAMETER	TO	FROM	N82LS10 N82LS11			S82LS10 S82LS11			N93L415 N93L425			S93L415 S93L425			
			Min	Typ <sup>2</sup>	Max	Min	Typ <sup>2</sup>	Max	Min	Typ <sup>2</sup>	Max	Min	Typ <sup>2</sup>	Max	
$T_{AA}$ Access time $T_{CE}$ Address Chip enable	Output	Address Chip enable		30	45		30	70		30	60		70	45	ns
$T_{CD}$ Disable time	Output	Chip enable		15	30		15	45			40			50	ns
$T_{WD}$ Response time	Output	Write enable		20	30		20	45			45			45	ns
$T_{WR}$ Write recovery time				20	30		20	45			45			55	ns
Setup and hold time															ns
$T_{WSA}$ Setup time $T_{WHA}$ Hold time	Write enable	Address	5	0		10	0		5	0		10	10		
$T_{WSD}$ Setup time $T_{WHD}$ Hold time	Write enable	Data in	40	30		55	35		50			60	10		
$T_{WSC}$ Setup time $T_{WHC}$ Hold time	Write enable	CE	5	0		5	0		5			10	10		
Pulse width $T_{WP}$ Write enable <sup>10</sup>			35	25		50	25		45			50			ns

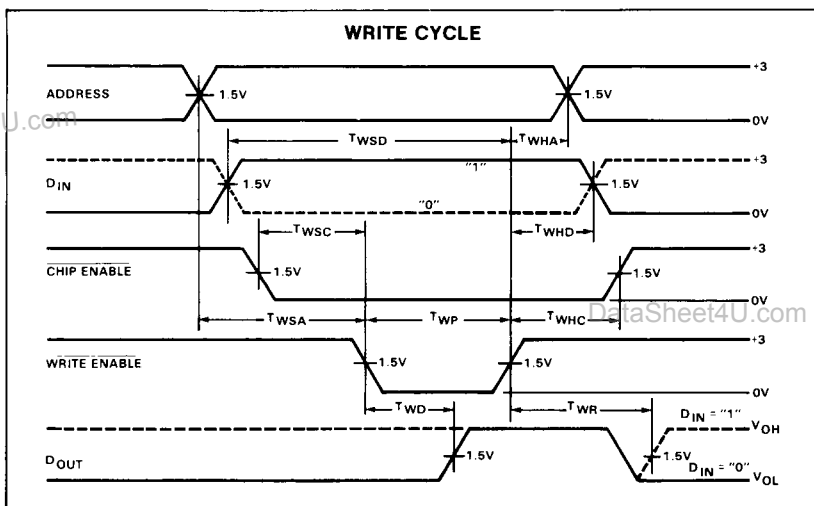
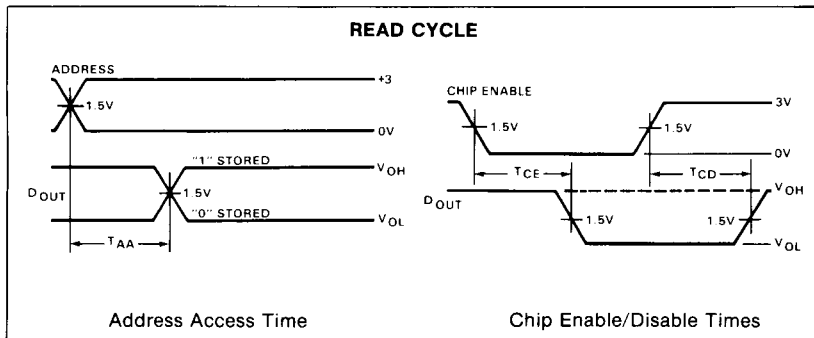
**NOTES**

- All voltage values are with respect to network ground terminal.
- All typical values are at  $V_{CC} = 5V$ ,  $T_A = 25^\circ C$ .
- Test each input one at a time.
- Measured with a logic low stored. Output sink current is supplied through a resistor to  $V_{CC}$ .
- Measured with  $V_{IL}$  applied to CE and a logic high stored.
- Measured with  $V_{IH}$  applied to CE.
- Duration of the short circuit should not exceed 1 second.
- $I_{CC}$  is measured with the write enable and memory enable inputs grounded, all other inputs at 4.5V, and the output open.
- The operating ambient temperature ranges are guaranteed with transverse air flow exceeding 400 linear feet per minute and a 2-minute warm-up. Typical thermal resistance values of the package at maximum temperature are:  
 $\theta_{JA}$  junction to ambient at 400fpm air flow- $50^\circ C/watt$   
 $\theta_{JA}$  junction to ambient-still air- $90^\circ C/watt$   
 $\theta_{JC}$  junction to case- $20^\circ C/watt$
- Minimum required to guarantee a Write into the slowest bit.

**TEST LOAD CIRCUIT****VOLTAGE WAVEFORM**

**1024-BIT LOW POWER BIPOLAR RAM (1024X1)****82LS10/93L415 (O.C.)****82LS11/93L425 (I.S.)**

82LS10/82LS11-F,N, • 93L415/93L425-F,N

**TIMING DIAGRAMS****MEMORY TIMING DEFINITIONS**

- T<sub>WR</sub>** Delay between end of Write Enable pulse and when Data Output becomes valid. (Assuming Address still valid—not as shown.)
- T<sub>CE</sub>** Delay between beginning of Chip Enable low (with Address valid) and when Data Output becomes valid.
- T<sub>CD</sub>** Delay between when Chip Enable becomes high and Data Output is in off state.
- T<sub>AA</sub>** Delay between beginning of valid Address (with Chip Enable low) and when Data Output becomes valid.
- T<sub>WSC</sub>** Required delay between beginning of valid Chip Enable and beginning of Write Enable pulse.
- T<sub>WHD</sub>** Required delay between end of Write Enable pulse and end of valid Input Data.
- T<sub>WP</sub>** Width of Write Enable pulse.
- T<sub>WSA</sub>** Required delay between beginning of valid Address and beginning of Write Enable pulse.
- T<sub>WSD</sub>** Required delay between beginning of valid Data Input and end of Write Enable pulse.
- T<sub>WD</sub>** Delay between beginning of Write Enable pulse and when Data Output is in off state.
- T<sub>WHC</sub>** Required delay between end of Write Enable pulse and end of Chip Enable.
- T<sub>WHA</sub>** Required delay between end of Write Enable pulse and end of valid Address.

**BIPOLAR MEMORY**